

— お詫びと訂正 —

学会誌掲載記事正誤表

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- 日本銅学会誌「銅と銅合金」第 64 巻 1 号(2025) p. 83-87.
「W/ODS-Cu ブレージング界面における接合拡散影響部の三次元組織解析」 嶋田 雄介 他

- ・ P. 83 タイトル

誤	3D Structural Analysis of Diffusion Affected Zone at W/ODS-Cu Brazing Interface
正	3D Structural Analysis of the Interfacial Reaction Zone at the W/ODS-Cu Brazing Interface

- ・ P. 83 Abstract

誤	Consequently, the diffusion of nickel atoms, the raw material of the brazing material, obtained two characteristic microstructures: first, in the nickel atoms diffusion region, nickel was solidly dissolved by copper and enhanced the grain growth of copper while remaining in a dispersed oxide distribution. In the other, nickel formed an intermetallic compound NiW ₂ with tungsten and was distributed to cover the bonding interface.
正	Consequently, a near-interface region affected by Ni diffusion from BNi-6 and possible local melting/reaction during brazing, hereafter referred to as the interfacial reaction zone, was formed and exhibited two characteristic microstructural features. First, in the Ni-enriched Cu region, Ni was dissolved in the Cu matrix and promoted Cu grain growth while maintaining the dispersion of oxide particles. Second, Ni reacted with W to form the intermetallic compound NiW ₂ , which was distributed along the bonding interface.

- ・ P. 84 2.2 6 行目

誤	10 keV
正	10 kV

- ・ P. 84 2.2 18 行目

誤	200 keV
正	200 kV

• P. 84 Fig. 1 (a)

誤	<p>arrowhead 欠落 (b)Interface of diffusion affected zone</p>
正	<p>arrowhead 追加 (b)Interface of reaction zone</p>

• P. 84 Fig. 1 キャプション

誤	<p>A SEM secondary electron image (a), an IPF map (b) and KAM map showing local strain (c) obtained by EBSD of the diffusion affected area of the bonding.</p>
正	<p>A SEM secondary electron image (a), an IPF map (b) and KAM map showing local strain (c) obtained by EBSD of the interfacial reaction zone of the bonding.</p>

• P. 85 Fig. 2 キャプション

誤	<p>A HAADF-STEM image of the diffusion affected area of the bonding. The results of phase analysis by electron diffraction and EDS from A to E in the figure are shown on the right.</p>
正	<p>A HAADF-STEM image of the interfacial reaction zone of the bonding. The results of phase analysis by SAED patterns and EDS from A to E in the figure are shown on the right.</p>

• P. 85 Fig. 3 キャプション

誤	<p>HAADF-STEM image (a) and LAADF-STEM image (b) obtained from diffusion affected area.</p>
正	<p>HAADF-STEM image (a) and LAADF-STEM image (b) obtained from the interfacial reaction zone.</p>

• P. 87 参考文献[7]

誤	[7] Y. Shimada, M. Kazukawa, Y. Hishinuma, K. Ikeda, H. Noto, B. Ma, M. Takeguchi, T. Muroga and T. J. Konno : Multiscale structural characterization of yttria dispersed copper alloys fabricated by hot isostatic processing of mechanically alloyed powders, <i>Materialia</i> 14(2020), 100892.
正	[7] M. Sato, Y. Shimada, Y. Hishinuma and N. Masahashi: Fabrication of oxide dispersion strengthened copper alloy powders by atmosphere-controlled gas atomization, <i>Mater. Trans.</i> , 66 (2025), 1036–1042.